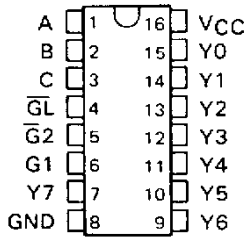
SN54HC237, SN74HC237
3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS WITH ADDRESS LATCHES

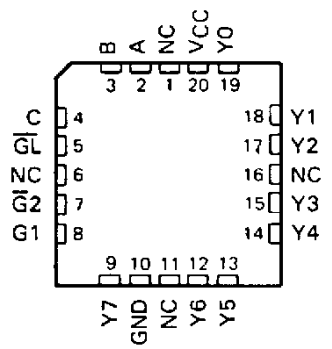
D2804, MARCH 1984—REVISED JUNE 1989

- Combines Decoder and 3-Bit Address Latch
- Incorporates 2 Output Enables to Simplify Cascading
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

SN54HC237 . . . J PACKAGE
SN74HC237 . . . D† OR N PACKAGE
(TOP VIEW)



SN54HC237 . . . FK PACKAGE
(TOP VIEW)



NC—No internal connection

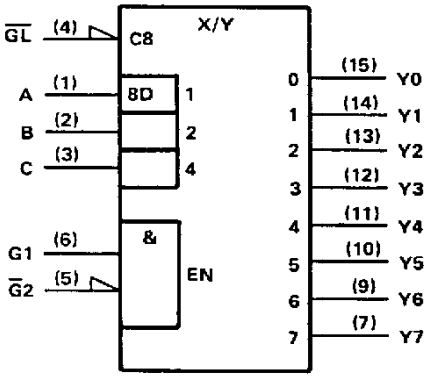
†Contact the factory for D availability.

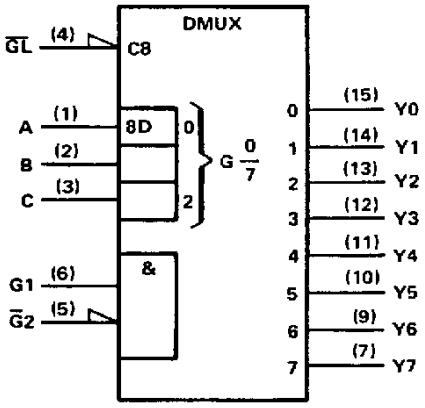
description

The 'HC237 is a three-line to eight-line decoder/demultiplexer with latches on the three address inputs. When the latch-enable ($\overline{GL}$) is low, the 'HC237 acts as a decoder/demultiplexer. When $\overline{GL}$ goes from low to high, the address present at the select inputs (A, B, and C) is stored in the latches. Further address changes are ignored as long as $\overline{GL}$ remains high. The output enable controls, G1 and $\overline{G2}$, control the outputs independently of the select or latch-enable inputs. All of the outputs are forced low if G1 is low or $\overline{G2}$ is high. The 'HC237 is ideally suited for implementing glitch-free decoders in strobed (stored-address) applications in bus-oriented systems.

The SN54HC237 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74HC237 is characterized for operation from −40°C to 85°C.

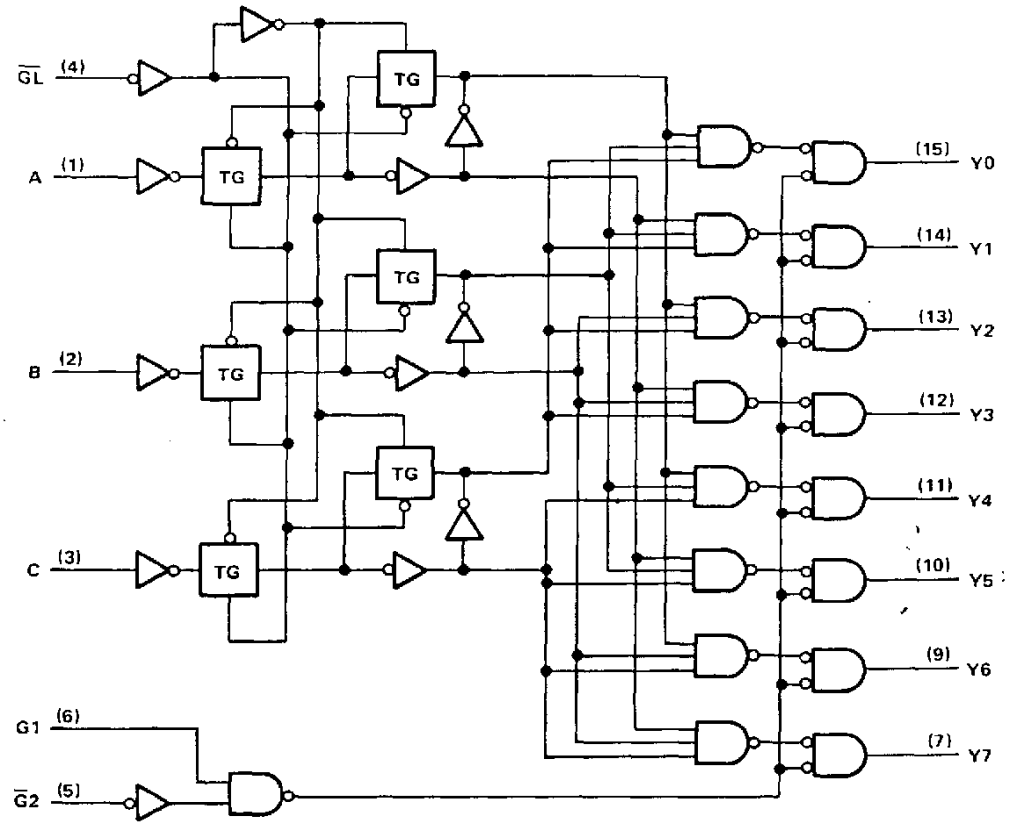
logic symbols (alternatives)‡





‡These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for D, J, and N packages.

FUNCTION TABLE

INPUTS						OUTPUTS							
ENABLE			SELECT										
GL	G1	G2	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	X	H	X	X	X	L	L	L	L	L	L	L	L
X	L	X	X	X	X	L	L	L	L	L	L	L	L
L	H	L	L	L	L	H	L	L	L	L	L	L	L
L	H	L	L	L	H	L	H	L	L	L	L	L	L
L	H	L	L	H	L	L	L	H	L	L	L	L	L
L	H	L	L	H	H	L	L	L	H	L	L	L	L
L	H	L	H	L	L	L	L	L	L	H	L	L	L
L	H	L	H	L	H	L	L	L	L	L	H	L	L
L	H	L	H	H	L	L	L	L	L	L	L	H	L
L	H	L	H	H	H	L	L	L	L	L	L	L	H
H	H	L	X	X	X	Outputs corresponding to stored address, L; all others, H							

absolute maximum ratings over operating free-air temperature range†

Supply voltage, V_{CC} . . . . . −0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) . . . . . ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) . . . . . ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . . ±25 mA
Continuous current through V_{CC} or GND pins . . . . . ±50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package . . . . . 300°C
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package . . . . . 260°C
Storage temperature range . . . . . −65°C to 150°C

†Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54HC237			SN74HC237			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		2	5	6	2	5	6	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5			1.5			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 6 V	4.2			4.2			
V_{IL}	Low-level input voltage	V_{CC} = 2 V	0		0.3	0		0.3	V
		V_{CC} = 4.5 V	0		0.9	0		0.9	
		V_{CC} = 6 V	0		1.2	0		1.2	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
t_t	Input transition (rise and fall) times	V_{CC} = 2 V	0		1000	0		1000	ns
		V_{CC} = 4.5 V	0		500	0		500	
		V_{CC} = 6 V	0		400	0		400	
T_A	Operating free-air temperature		−55		125	−40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54HC237		SN74HC237		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL}, I_{OH} = −20 μA	2 V	1.9	1.998		1.9		1.9		V
		4.5 V	4.4	4.499		4.4		4.4		
		6 V	5.9	5.999		5.9		5.9		
	$V_I = V_{IH}$ or V_{IL}, I_{OH} = −4 mA	4.5 V	3.98	4.30		3.7		3.84		
	$V_I = V_{IH}$ or V_{IL}, I_{OH} = −5.2 mA	6 V	5.48	5.80		5.2		5.34		
V_{OL}	$V_I = V_{IH}$ or V_{IL}, I_{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	V
		4.5 V		0.001	0.1		0.1		0.1	
		6 V		0.001	0.1		0.1		0.1	
	$V_I = V_{IH}$ or V_{IL}, I_{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
	$V_I = V_{IH}$ or V_{IL}, I_{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I_I	$V_I = V_{CC}$ or 0	6 V		±0.1	±100		±1000		±1000	nA
I_{CC}	$V_I = V_{CC}$ or 0, I_O = 0	6 V			8		160		80	μA
C_i		2 to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V_{CC}	T_A = 25°C			SN54HC237		SN74HC237		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{GL}$ low	2 V	80			120		100		ns
		4.5 V	16			24		20		
		6 V	14			20		17		
t_{su}	Setup time, A, B, or C before $\overline{GL}$↑	2 V	75			115		95		ns
		4.5 V	15			23		19		
		6 V	13			20		16		
t_h	Hold time, A, B, and C after $\overline{GL}$↑	2 V	5			5		5		ns
		4.5 V	5			5		5		
		6 V	5			5		5		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), C_L = 50 pF (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			SN54HC237		SN74HC237		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A, B, C	Any	2 V		91	190		285		240	ns
			4.5 V		23	38		57		48	
			6 V		17	32		48		41	
t_{pd}	$\overline{G}2$	Any	2 V		66	145		220		181	ns
			4.5 V		18	29		44		36	
			6 V		13	25		37		31	
t_{pd}	G1	Any	2 V		68	145		220		181	ns
			4.5 V		18	29		44		36	
			6 V		14	25		37		31	
t_{pd}	$\overline{GL}$	Any	2 V		92	190		285		240	ns
			4.5 V		24	38		57		48	
			6 V		19	32		48		41	
t_t		Any	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

C_{pd}	Power dissipation capacitance	No load, T_A = 25°C	85 pF typ

NOTE 1: Load circuit and voltage waveforms are shown in Section 1.

IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.